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(71) Applicant (for all designated States except US): **PPG INDUSTRIES OHIO, INC.** [US/US]; 3800 West 143rd Street, Cleveland, Ohio 44111 (US).

(72) Inventors: **LI, Yuzhuo**; 1101 River Road, Norwood, New York 13668 (US). **HELLRING, Stuart D.**; 130 Oak Park Place, Pittsburgh, Pennsylvania 15243 (US). **KELEHER, Jason**; 1821 Misty Ridge Lane, Aurora, Illinois 60504 (US). **ZHANG, Tianxi**; 1630 Ne Valley Road, Apartment N101, Pullman, Washington 99163 (US).

(74) Agents: **ALTMAN, Deborah M.** et al.; PPG Industries, Inc., Law Department, One Ppg Place - 39th Floor, Pittsburgh, Pennsylvania 15272-0001 (US).

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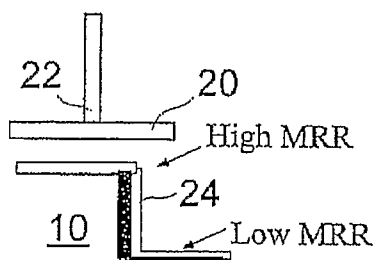
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(54) Title: CHEMICALLY MODIFIED POLISHING PAD FOR CHEMICAL MECHANICAL POLISHING



comprising a polyamine, a polyelectrolyte, and/or an amino acid. A method of making the CMP pad (20) and the CMP pad (20) formed thereby is also disclosed.

(57) Abstract: A method of CMP of a substrate surface includes providing a polishing pad (20) having a polishing layer (26), that may be substantially free of abrasive particles, with a functional group (30) chemically bonded (covalent or ionic) to the polishing layer (26). The functional group (30) acts as an activator or catalyst for a compound of a polishing slurry (24) to exhibit a higher material removal rate for removing selected portions of the surface of the substrate (10) than exhibited in CMP of a substantially identical substrate (10) in the presence of a substantially identical polishing slurry (24) and a polishing pad (20) wherein the substantially identical polishing layer (26) does not have the functional group (30). The functional group (30) may be derived from a compound